

Industry: substrates, Semiconductors Field of Business : R&D, Quality Assurance

Flying Probe Tester + Heating System

Test system that heats up the substrate while measuring its resistance

Problems

- Thermal stress tests are performed on substrates, especially when used in challenging environments such as the automotive and smartphone industries.
- When the thermally expanded substrate undergoes a cooling process, it will return to its original state. If the defect is apparent at high temperatures, it will be considered acceptable at room temperature.
- The burn-in test requires the production of specialized fixtures, which significantly increases production costs during R&D and prototype phases when designs are frequently changing.

Solutions

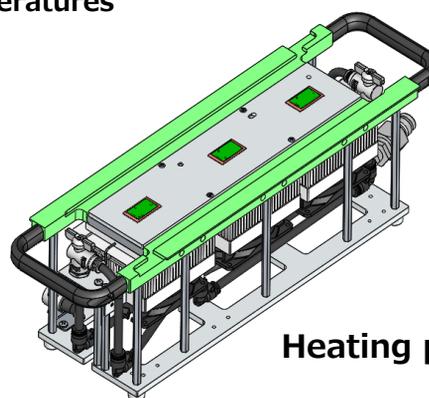
- Flying probe tester with internal heating device
- Resistance testing is performed while the substrate is heated
- Easy to accommodate design modifications

Features

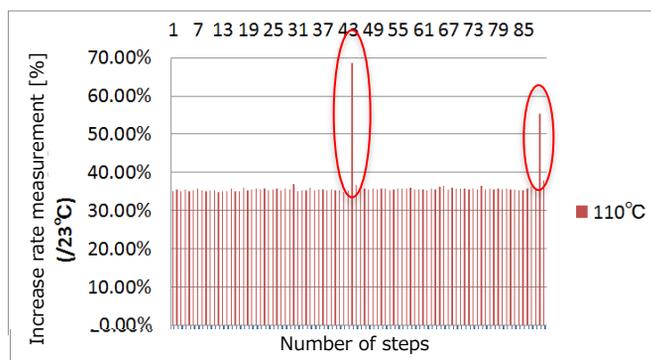
- Four-wire micro-resistance test with a minimum measurement point diameter of $\Phi 28\mu\text{m}^{*1}$
- $40\mu\Omega$ ~ high precision micro-resistance testing
- Minimal needle impact due to the newest combination of test needles
- Micro-resistance testing at high temperatures



FA1813
Flying Probe Tester



Heating plate



Detects a distinctive rise in resistance on a specific pattern

*1: Possible under certain conditions